

Form PTO-1449

INFORMATION DISCLOSURE  
IN AN APPLICATION  
(Use several sheets if necessary)

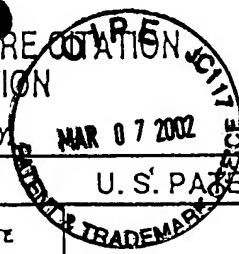
Docket Number (Optional)  
MEGIC-01-003

Applicant  
Mou-Shiung Lin et al.

Filing Date  
01/19/02

Application Number  
10/054,001

Group Art Unit  
28TT



U. S. PATENT DOCUMENTS 2827

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<div></div>						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

AC	Microelectronic Packaging Handbook, Chapter 9, R.R. Tummala et al., Van Nostrand Reinhold, NY, 1989,
AC	pp. 673 - 725.
AC	Novel Microelectronic Packaging Method for Reduced Thermomechanical Stresses on Low Dielectric Constant Materials, R.M. Emery, et al., Intel Corp., Chandler, AZ.

EXAMINER  
Alonso Chambliss

DATE CONSIDERED  
11/21/03

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.